

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	3	(radiation adj plate) with (leadfram or (lead adj frame)) with (insulation adj sheet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 10:51
L6	3	(radiation adj plate) with (leadframe or (lead adj frame)) with (insulation adj sheet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 10:52
L7	11	(radiation adj plate) with (leadframe or (lead adj frame)) with (sheet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 10:57
L8	338	yoshihisa and yamashita	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 10:57
L9	10	yoshihisa and yamashita and ((thermal or thermall) adj (conductive or conducting))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 10:59
L10	16895	((thermal or thermall) adj (conductive or conducting))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 10:59
L11	421	((thermal or thermall) adj (conductive or conducting)) and (leadframe or (lead adj frame))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:00
L12	5	((thermal or thermall) adj (conductive or conducting)) and (leadframe or (lead adj frame)) and (radiation adj plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:00
L13	294	(radiation adj plate).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:01

L14	13	(radiation adj plate).clm. and (leadframe or (lead adj frame)). clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:01
L15	35	(((thermal or thermally) adj (conductive or conducting)) with (leadframe or (lead adj frame)) with plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:04
L16	8	(((thermal or thermally) adj (conductive or conducting)) with (leadframe or (lead adj frame)) with plate).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:09
L17	4	(((thermal or thermally) adj (conductive or conducting)) with (leadframe or (lead adj frame)) with plate) with (insulating or dielectric or insulator) with sheet	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:10
L18	10	(((thermal or thermally) adj (conductive or conducting)) with (leadframe or (lead adj frame)) with plate) with (insulating or dielectric or insulator)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:10
L19	22	(((thermal or thermally) adj (conductive or conducting)) with (leadframe or (lead adj frame)) with plate) with (insulating or dielectric or insulator or resin or epoxy or adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:13
L20	7	(((thermal or thermally) adj (conductive or conducting)) with (leadframe or (lead adj frame)) with plate) with (insulating or dielectric or insulator or resin or epoxy or adhesive) and ((remove or removing or removed or cut or cutting) near5 plate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:14
L21	4	(((thermal or thermally) adj (conductive or conducting)) with (leadframe or (lead adj frame)) with plate) with (insulating or dielectric or insulator or resin or epoxy or adhesive) and ((remove or removing or removed or cut or cutting) near5 plate near5 portion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:15

L22	4	((thermal or thermally) adj (conductive or conducting)) with (leadframe or (lead adj frame)) with plate) with (insulating or dielectric or insulator or resin or epoxy or adhesive) and ((remove or removing or removed or cut or cutting) near5 plate near5 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:16
L23	4	((thermal or thermally) adj (conductive or conducting)) with (leadframe or (lead adj frame)) with (heat\$5 or plate)) with (insulating or dielectric or insulator or resin or epoxy or adhesive) and ((remove or removing or removed or cut or cutting) near5 plate near5 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:16
L24	5	((thermal or thermally) adj (conductive or conducting)) with (leadframe or (lead adj frame)) with (heat\$5 or plate)) with (insulating or dielectric or insulator or resin or epoxy or adhesive) and ((remove or removing or removed or cut or cutting) near5 (heat\$5 or plate) near5 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:17
L25	5	((thermal or thermally) adj (conductive or conducting)) with (leadframe or (lead adj frame)) with (heat\$5 or radiation or plate)) with (insulating or dielectric or insulator or resin or epoxy or adhesive) and ((remove or removing or removed or cut or cutting) near5 (radiation or heat\$5 or plate) near5 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:18
L26	87	(leadframe or (lead adj frame)) with (heat\$5 or radiation or plate) with (insulating or dielectric or insulator or resin or epoxy or adhesive) and ((remove or removing or removed or cut or cutting) near5 (radiation or heat\$5 or plate) near5 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:19
L27	24	(leadframe or (lead adj frame)) with (heat\$5 or radiation or plate) with (insulating or dielectric or insulator or resin or epoxy or adhesive) and ((remove or removing or removed or cut or cutting) near2 (radiation or heat\$5 or plate) near2 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:21

L28	4	((leadframe or (lead adj frame)) with (heat\$5 or radiation or plate) with (insulating or dielectric or insulator or resin or epoxy or adhesive) with sheet) and ((remove or removing or removed or cut or cutting) near2 (radiation or heat\$5 or plate) near2 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:22
L29	4	((leadframe or (lead adj frame)) same (heat\$5 or radiation or plate) with (insulating or dielectric or insulator or resin or epoxy or adhesive) with sheet) and ((remove or removing or removed or cut or cutting) near2 (radiation or heat\$5 or plate) near2 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:22
L30	4	((leadframe or (lead adj frame)) same (heat\$5 or radiation or plate) same (insulating or dielectric or insulator or resin or epoxy or adhesive) with sheet) and ((remove or removing or removed or cut or cutting) near2 (radiation or heat\$5 or plate) near2 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:22
L31	4	((leadframe or (lead adj frame)) same (heat\$5 or radiation or plate) same (insulating or dielectric or insulator or resin or epoxy or adhesive) same sheet) and ((remove or removing or removed or cut or cutting) near2 (radiation or heat\$5 or plate) near2 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:22
L32	4	((leadframe or (lead adj frame)) same (slug or heat\$5 or radiation or plate) same (insulating or dielectric or insulator or resin or epoxy or adhesive) same sheet) and ((remove or removing or removed or cut or cutting) near2 (radiation or heat\$5 or slug or plate) near2 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:23
L33	10	((leadframe or (lead adj frame)) and (slug or heat\$5 or radiation or plate) same (insulating or dielectric or insulator or resin or epoxy or adhesive) same sheet) and ((remove or removing or removed or cut or cutting) near2 (radiation or heat\$5 or slug or plate) near2 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:23

L34	21	((leadframe or (lead adj frame)) and (slug or heat\$5 or radiation or plate) and (insulating or dielectric or insulator or resin or epoxy or adhesive) same sheet) and ((remove or removing or removed or cut or cutting) near2 (radiation or heat\$5 or slug or plate) near2 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:23
L35	37	((leadframe or (lead adj frame)) and (slug or heat\$5 or radiation or plate) and (insulating or dielectric or insulator or resin or epoxy or adhesive) and sheet) and ((remove or removing or removed or cut or cutting) near2 (radiation or heat\$5 or slug or plate) near2 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:24
L36	81	((leadframe or (lead adj frame)) and (slug or heat\$5 or radiation or plate) and (insulating or dielectric or insulator or resin or epoxy or adhesive)) and ((remove or removing or removed or cut or cutting) near2 (radiation or heat\$5 or slug or plate) near2 (end or portion))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:24
L37	31	"6060150"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:33
L38	13	"6291880"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/20 11:33
L39	5	("6201696" "6291880" "6366443").PN. OR ("6700182").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/20 11:39
L40	1	"5576578"	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/20 11:40
L41	30	"6060150"	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/20 11:40